



# Product Change Notification

**Change Notification #: 116039 - 02**

**Change Title:** Intel® Compute Module HNS2600BPB24,  
Intel® Compute Module HNS2600BPQ24,  
Intel® Compute Module HNS2600BPS,  
Intel® Compute Module HNS2600BPS24,  
Intel® Server System HNS2600BPB,  
Intel® Server System HNS2600BPQ,  
**PCN 116039-02, Product Design, Order Code,  
Updated the Heat Sink and Order Code Change,  
Reason for Revision: To make PCN available to  
the public**

**Date of Publication:** April 19, 2018

## Key Characteristics of the Change:

Product Design, Order Code

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material: *</b>	February 28, 2018
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\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

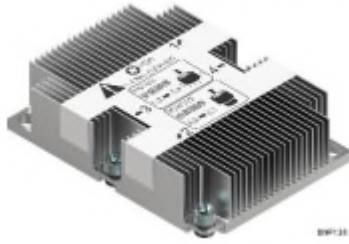
**Reason for Revision: This PCN was initially restricted and not available to the general public. This revision changes the security settings to make it available to the public.**

Intel is implementing the following change on the Intel® Compute Module HNS2600BPB, Intel® Compute Module HNS2600BPB24, Intel® Compute Module HNS2600BPS, Intel® Compute Module HNS2600BPS24, Intel® Compute Module HNS2600BPQ, and Intel® Compute Module HNS2600BPQ24:

- Update of the Front Heat Sink (for CPU 2 use only) from 1U standard Ex-Al 78mm x 108mm heat sink FXXEA78X108HS to 1U Standard Cu/Al 78mm x 108mm 26fin Heat Pipe FXX2678X108HS. The new heat sink is the same in form factor and function to the previous one. See images below.

Pre-change heat sink:

iPC - FXXEA78X108HS



Post Change heat sink:

iPC - FXX2678X108HS



### Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

The products with the Heat Pipe heat sink will have a new ordering code.

Customers who desire to use the heat sink with the Heat Pipe capability should place orders using the new order code.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

### Products Affected / Intel Ordering Codes:

Product Code	Pre Change MM#	Pre Change TA	Post Change Product Code	Post Change MM#	Post Change TA
HNS2600BPQ	948901	J48509-003	HNS2600BPQ	976669	J48509-004
HNS2600BPB24	948903	J48508-003	HNS2600BPB24	976671	J48508-004
HNS2600BPQ24	948904	J48510-003	HNS2600BPQ24	976675	J48510-004
HNS2600BPB	948924	J48507-003	HNS2600BPB	976668	J48507-004
HNS2600BPS	952610	J48511-003	HNS2600BPS	976670	J48511-004
HNS2600BPS24	952611	J48513-003	HNS2600BPS24	976676	J48513-004

### PCN Revision History:

**Date of Revision:**

January 29, 2018

March 14, 2018

April 19, 2018

**Revision Number:**

00

01

02

**Reason:**

Originally Published PCN

Update Products Affected table with correct TA numbers

To make PCN available to the public



# Product Change Notification

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific/PRC Contact:** [apagccb@intel.com](mailto:apagccb@intel.com)

**Europe Email:** [eccb@intel.com](mailto:eccb@intel.com)

**Japan Email:** [jccb.ijkk@intel.com](mailto:jccb.ijkk@intel.com)

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